



NLX-5 BLUE POWER DIE

BXCA 45 x 45 mil

PRODUCT DATA SHEET

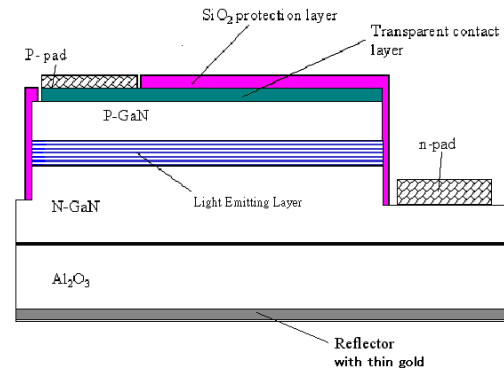
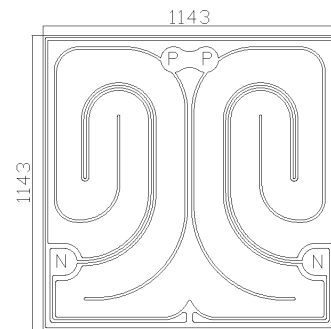
Features

- High lumen output and efficiency
- Long operating life
- 100% Tested and sorted by wavelength, power and forward voltage
- Lambertian emission pattern
- Compatible with Solder paste, solder preform or silver epoxy die attach
- Delivered on medium tack blue tape (20cm±10mm x 20 cm±10mm)

Applications

- General Illumination
- Street Lights
- Portable Lighting
- Architectural Lighting
- Directional Lighting
- Wide Area Lighting
- Display Backlighting
- Digital Camera Flash
- Automotive Lighting
- White LEDs

LED Chip Diagram



Mechanical Dimensions

Chip Size	1143 +30/-10 μm \times 1143 +30/-10 μm (45 mil x 45 mil)
Chip Thickness	150 \pm 10 μm (5.9 mil)
Au Pad Thickness	2.4 \pm 0.2 μm
Au Pad Diameter	P Pad (2X): 100 μm N Pad (2X): 105 μm

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Part Numbering and Bin Definitions

Bridgelux LED chips are sorted into the brightness and dominant wavelength bins shown below at $I_f = 350$ mA. Each blue tape contains die from only one brightness bin and one wavelength bin.

Each blue tape contains chips with 0.2 V forward voltage bins: 3.0 - 3.2 V, 3.2 - 3.4 V and 3.4 - 3.6 V. The typical forward voltage is 3.4 V and the maximum forward voltage ($V_f \text{ max}$) = 3.6 V.

Dominant Wavelength	Power Bin C (240 – 255 mW)	Power Bin D (255 – 295 mW)	Power Bin E (295 – 340 mW)
445 to 447.5nm	BXCA4545445-Cy-z	BXCA4545445-Dy-z	BXCA4545445-Ey-z
447.5 to 450nm	BXCA4545447-Cy-z	BXCA4545447-Dy-z	BXCA4545447-Ey-z
450 to 452.5nm	BXCA4545450-Cy-z	BXCA4545450-Dy-z	BXCA4545450-Ey-z
452.5 to 455nm	BXCA4545452-Cy-z	BXCA4545452-Dy-z	BXCA4545452-Ey-z
455 to 457.5nm	BXCA4545455-Cy-z	BXCA4545455-Dy-z	BXCA4545455-Ey-z
457.5 to 460nm	BXCA4545457-Cy-z	BXCA4545457-Dy-z	BXCA4545457-Ey-z
460 to 462.5nm	BXCA4545460-Cy-z	BXCA4545460-Dy-z	BXCA4545460-Ey-z
462.5 to 465nm	BXCA4545462-Cy-z	BXCA4545462-Dy-z	BXCA4545462-Ey-z

Product Nomenclature

B X C A 4 5 4 5 X X X - Y Y - Z

Where:

- BXCA: Designates product family
- 4545: Designates die size (45 mil x 45 mil)
- XXX: Designates dominant wavelength bin
- YY: Designates radiometric power bin
- Z: Designates forward voltage bin

Environmental Compliance

Bridgelux is committed to providing environmentally friendly products to the solid state lighting market. Bridgelux NLX-5 blue power die are compliant to the European Union directives on the restriction of hazardous substances in electronic equipment, namely the RoHS directive. Bridgelux will not intentionally add the following restricted materials to NLX-5 die products: lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls (PBB) or polybrominated diphenyl ethers (PBDE).

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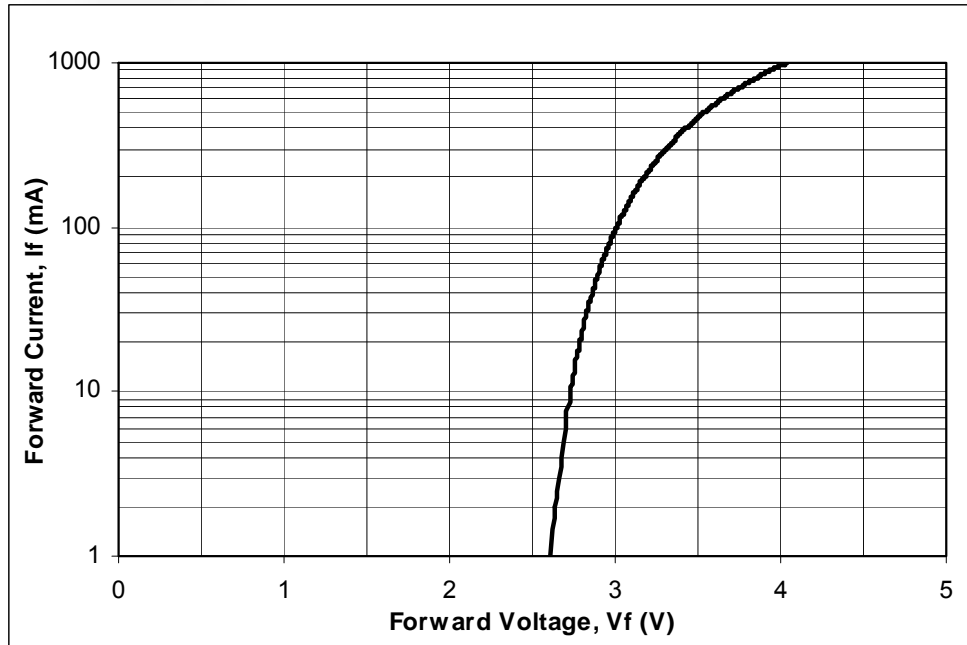


Figure 1: Forward current vs. forward voltage ($T_j = 25^\circ\text{C}$)

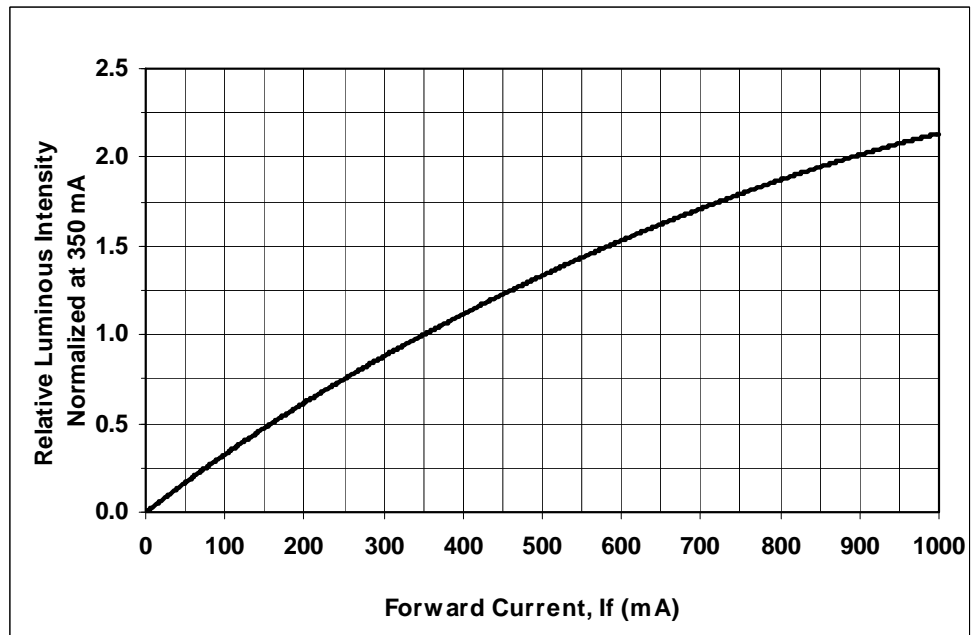


Figure 2: Relative luminous intensity vs. forward current (device tested on a probe station)

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Absolute Maximum Ratings

Parameter	Symbol	Maximum Rating	Condition
DC Forward Current	I_f	700 mA ¹	$T_j = 125^\circ\text{C}$
Junction Temperature	T_j	150°C	
Reverse Voltage	V_r	-5 V	$T_a = 25^\circ\text{C}$
Reverse Current	I_r	< 10 μA	$V_r = -5\text{ V}$
Assembly Process Temperature	325°C for < 5 seconds		
Storage Conditions (chip on tape) ⁶	0°C to +40°C ambient, RH < 65%		

Notes:

- Maximum drive current depends on junction temperature, die attach methods/materials, and lifetime requirements of the application.
- Bridgelux LED chips are Class 1 ESD sensitive.
- The typical spectra half-width of the NLX-5 blue power die is < 25 nm.
- Please consult the Bridgelux technical support team for information on how to optimize the light output of our chips in your package.
- Brightness values are measured in an integrating sphere using gold plated TO39 headers without encapsulation.
- Tapes should be stored in a vertical orientation, not horizontally stacked. Stacking of tapes can place excessive pressure on the bond pads of the LED, resulting in reduced wire bonding strength.

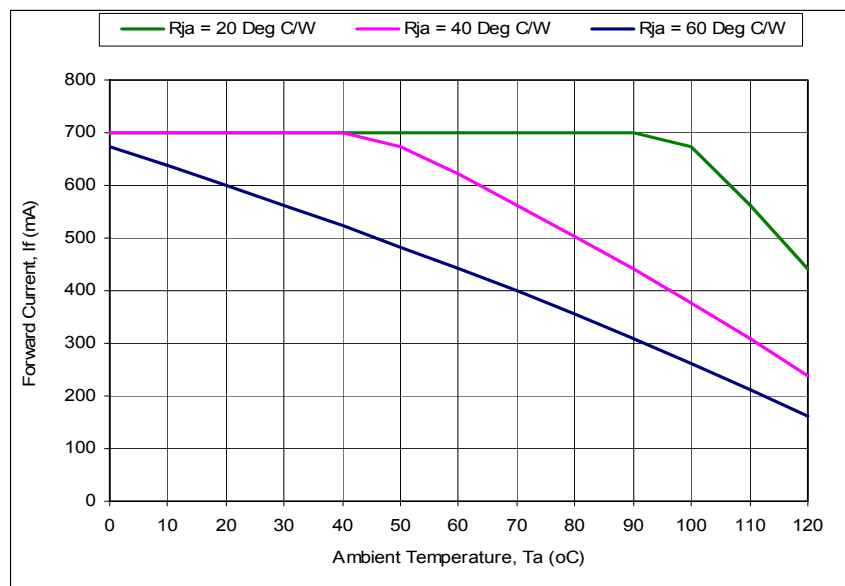


Figure 3: Current Derating Curve vs. Ambient Temperature (derating based on T_j max 150°C)

About Bridgelux

Bridgelux is a U.S. lighting company and leading provider of high-power, cost-effective and energy-efficient light-emitting diode (LED) solutions. Focused on bringing innovation to light, Bridgelux's proprietary epitaxy technology, advanced chip designs and leading-edge LED packaging technology have enabled the company to develop advanced solid-state lighting (SSL) products that offer superior quality, are lower in cost and environmentally friendly—all without compromising performance. In addition to LED chips, the company delivers a range of SSL light sources that customers can easily integrate into a variety of lighting applications that will open up new markets in solid-state lighting. Founded in 2002, Bridgelux is headquartered in Sunnyvale, California. For more information about the company, please visit www.bridgelux.com

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